

ABSTRACT OF THE DISCLOSURE

A composite heat sink devise includes a heat sink body formed of aluminum, the body having a pair of coplanar surfaces, and a thermally conductive solderable element, for example of copper, mechanically fixed to each of the coplanar surfaces. Each of the solderable elements has a first surface which is contiguous with one of the coplanar surfaces, and a
5 second surface which is soldered to a printed circuit board.

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